

Special Issue

Advanced Studies in Solder Joints

Message from the Guest Editors

Solder joints have been the key structural component in advanced packaging. Following Moore's Law leading the development of chip technology gradually approaching the physical limit in recent years, the realization of "More than Moore" through advanced packaging technology has become the main developing direction of electronic manufacturing. Significant advances in solder joints have been achieved as a result of interdisciplinary research in related fields of materials characterization, mechanical property, microelectronics technology, physics and chemistry, constitutive modeling, mathematical analysis and numerical methods. This Special Issue on "Advanced Studies in Solder Joints" intends to collect the latest developments in the field, written by well-known researchers who have contributed significantly on at least one of these specific topics - interfacial reaction mechanisms, microstructures and properties characterization, numerical modeling and simulations of solder joints in advanced electronic manufacturing and packaging.

Guest Editors

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Deadline for manuscript submissions

closed (31 December 2024)



Metals

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About the Journal

Message from the Editorial Board

Metallic materials play a vital role in the economic life of modern societies; contributions are sought on fresh developments that enhance our understanding of the fundamental aspects related to the relationships between processing, properties and microstructure – disciplines in the metallurgical field ranging from processing, mechanical behavior, phase transitions and microstructural evolution, nanostructures, as well as unique metallic properties – inspire general and scholarly interest among the scientific community.

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